

MOSFET Product Summary

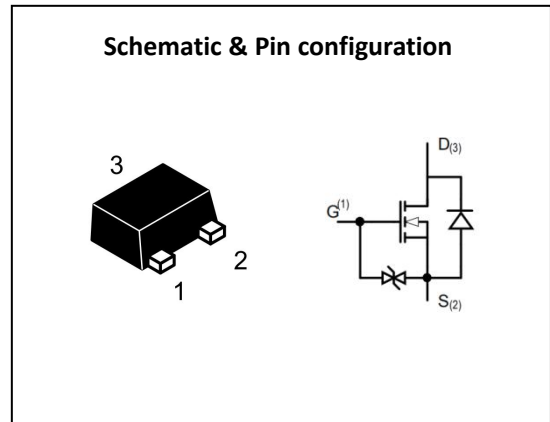
V_{DS}	I_D	$R_{DS(on)}$
60V	115mA	<3.0Ω@10V
		<3.5Ω@5.0V

Features and benefits

- 60V Trench DMOS technology
- Low on-state resistance
- Fast switching
- Improved dv/dt capability
- ESD Rating: 1000V HBM
- Pb-Free, RoHS Compliant

Applications

- Load switch
- Power management
- Battery operated systems
- Level Shift Circuits
- DC-DC Converter



Maximum Ratings ($T_A = 25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	±20	V
Continuous Drain Current <small>(note1)</small>	I_D	115	mA
Pulsed Drain Current <small>($t_p=10\text{-s}$)</small>	I_{DM}	800	mA
Power Dissipation <small>(note1)</small>	P_D	150	mW
Thermal Resistance from Junction to Ambient <small>(note1)</small>	$R_{\theta JA}$	833	$^\circ\text{C/W}$
Junction temperature	T_j	125	$^\circ\text{C}$
Storage temperature	T_{stg}	-50 to +150	$^\circ\text{C}$

Electrical Characteristics (T_A = 25 °C, unless otherwise specified)

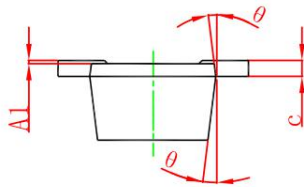
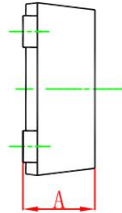
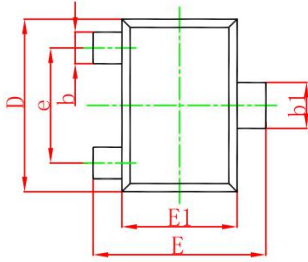
Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
STATIC CHARACTERISTIC						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	60			V
Zero gate voltage drain current	I _{DSS}	V _{DS} = 48V, V _{GS} = 0V			1	μA
Gate-body leakage current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±10	μA
Gate threshold voltage <small>(note2)</small>	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	1.0	1.8	2.5	V
Drain-source on-resistance <small>(note2)</small>	R _{DS(on)}	V _{GS} = 10V, I _D = 0.3A			3	Ω
		V _{GS} = 5V, I _D = 0.3A			3.5	Ω
Maximum Continuous Drain to Source Diode Forward Current	I _S	--			0.15	A
Maximum Pulsed Drain to Source Diode Forward Current	I _{SM}	--			0.8	A
Diode forward voltage	V _{SD}	I _S = 0.15A, V _{GS} = 0V			1.2	V
DYNAMIC CHARACTERISTICS <small>(note3)</small>						
Input capacitance	C _{iss}	V _{DS} = 10V, V _{GS} = 0V, f = 1MHz			40	pF
Output capacitance	C _{oss}				30	pF
Reverse transfer capacitance	C _{rss}				10	pF
SWITCHING CHARACTERISTICS <small>(note3)</small>						
Turn-on delay time	t _{d(on)}	V _{GS} = 10V, V _{DS} = 30V, I _D = 200mA, R _G = 3.3Ω			10	nS
Turn-on rise time	t _r				20	nS
Turn-off delay time	t _{d(off)}				15	nS
Turn-off fall time	t _f				10	nS
GATE-SOURCE ZENER DIODE						
Gate-Source Breakdown Voltage	B _{VGS0}	I _{GS} = ±1mA (Open Drain)	±20		±30	V

Notes:

1. Surface mounted on FR4 board using the minimum recommended pad size.
2. Pulse Test : Pulse Width=300μs, Duty Cycle=2%.
3. These parameters have no way to verify.

Package Outline Dimensions

SOT723



Symbol	Dimensions (mm)	
	Min	Max
A	0.42	0.50
A1	0.00	0.05
b	0.16	0.28
b1	0.25	0.35
c	0.07	0.16
D	1.10	1.30
e	0.8TYP	
E	1.10	1.30
E1	0.75	0.85
θ	8°	10°